## **NSR10F20NXT5G**

## **Schottky Barrier Diode**

These Schottky barrier diodes are optimized for low forward voltage drop and low leakage current and are offered in a Chip Scale Package (CSP) to reduce board space. The low thermal resistance enables designers to meet the challenging task of achieving higher efficiency and meeting reduced space requirements.

#### **Features**

- Low Forward Voltage Drop 430 mV @ 1.0 A
- Low Reverse Current 20 μA @ 10 V VR
- 1.0 A of Continuous Forward Current
- ESD Rating Human Body Model: Class 3B
  - Machine Model: Class C
- High Switching Speed
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

## **Typical Applications**

- LCD and Keypad Backlighting
- Camera Photo Flash
- Buck and Boost dc-dc Converters
- Reverse Voltage and Current Protection
- Clamping & Protection

### **Markets**

- Mobile Handsets
- MP3 Players
- Digital Camera and Camcorders
- Notebook PCs & PDAs
- GPS

#### **MAXIMUM RATINGS**

Rating		Symbol	Value	Unit
Reverse Voltage		$V_{R}$	20	V
Forward Current (DC)		ΙF	1.0	Α
Forward Surge Current (60 Hz	I <sub>FSM</sub>	18	Α	
Repetitive Peak Forward Current (Pulse Wave = 1 sec, Duty Cycle = 66%)		I <sub>FRM</sub>	4.0	Α
ESD Rating: Human Bo Machine M		ESD	> 8 > 400	kV V

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

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## **20 V SCHOTTKY BARRIER DIODE**





DSN<sub>2</sub> (0502)CASE 152AD

### **MARKINGS DIAGRAM**

PIN 1



= Specific Device Code 10F20 = Year Code

PIN 1



AD = Specific Device Code

M = Date Code

#### **ORDERING INFORMATION**

Device	Package	Shipping†
NSR10F20NXT5G	DSN2 (Pb-Free)	5000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

### NSR10F20NXT5G

### THERMAL CHARACTERISTICS

Characteristic	Symbol	Min	Тур	Max	Unit
Thermal Resistance Junction-to-Ambient (Note 1) Total Power Dissipation @ T <sub>A</sub> = 25°C	R <sub>θJA</sub> P <sub>D</sub>			228 548	°C/W mW
Thermal Resistance Junction-to-Ambient (Note 2) Total Power Dissipation @ T <sub>A</sub> = 25°C	R <sub>θJA</sub> P <sub>D</sub>			85 1.47	°C/W W
Storage Temperature Range	T <sub>stg</sub>			-40 to +125	°C
Junction Temperature	TJ			+150	°C

- 1. Mounted onto a 4 in square FR-4 board 50 mm sq. 1 oz. Cu 0.06" thick single sided. Operating to steady state.
- 2. Mounted onto a 4 in square FR-4 board 1 in sq. 1 oz. Cu 0.06" thick single sided. Operating to steady state.

## **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
Reverse Leakage (V <sub>R</sub> = 10 V) (V <sub>R</sub> = 20 V)	I <sub>R</sub>			20 100	μΑ
Forward Voltage (I <sub>F</sub> = 0.5 A) (I <sub>F</sub> = 1.0 A)	V <sub>F</sub>		0.380 0.430	0.400 0.450	V

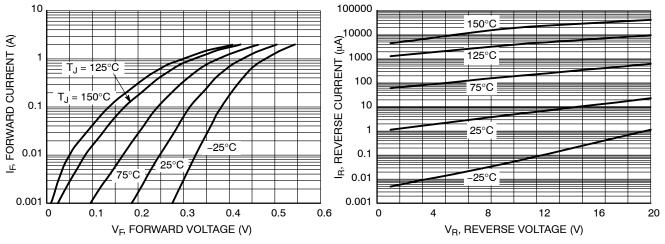


Figure 1. Forward Voltage

Figure 2. Typical Reverse Current

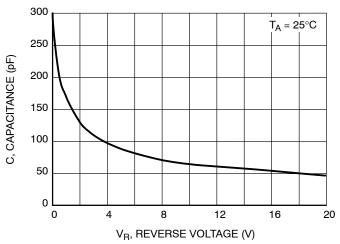
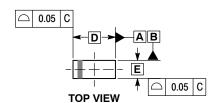


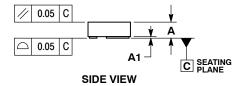
Figure 3. Typical Capacitance

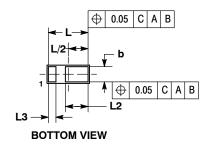


**DSN2**, **1.4x0.6**, **0.75P** CASE 152AD ISSUE C

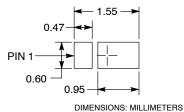
**DATE 24 APR 2017** 







#### **MOUNTING FOOTPRINT\***



See Application Note AND8464/D for more mounting details

#### NOTES

- DIMENSIONING AND TOLERANCING PER
   ASME Y14.5M. 1994.
- ASME Y14.5M, 1994. DONTROLLING DIMENSION: MILLIMETERS.

	MILLIMETERS			
DIM	MIN	MAX		
Α	0.25	0.31		
A1	0.05			
b	0.45	0.55		
D	1.40 BSC			
Е	0.60 BSC			
L	1.20	1.30		
L2	0.70	0.80		
L3	0.20	0.30		

# GENERIC MARKING DIAGRAM1\*

## GENERIC MARKING DIAGRAM2\*



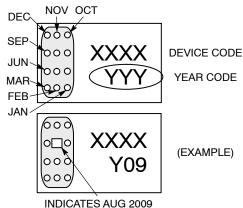


XXXX = Specific Device Code YYY = Year Code XX = Specific Device Code

M = Date Code

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present. Some products may not follow the Generic Marking.

# CATHODE BAND MONTH CODING



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DESCRIPTION:	DSN2, 1.4X0.6, 0.75P		PAGE 1 OF 1

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<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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